

Product Change Notice

Issue Date: 31-MAY-2024**Change Description:**

Replacement of manufacturing site, LED die and epoxy for ChipLED part numbers listed below.

Parts Affected:

HSMF-C180	HSMF-C181	HSMF-C182	BSMF-C183
HSMF-C184	HSMF-C185	HSMF-C186	HSMF-C187
HSMF-C188	HSMF-C189	QSMF-C182-000C1	BSMF-C18B-000AA
HSMQ-C380	QSMQ-V381	HSMF-C124	BSMF-C124

Description and Extent of Change:

Details of the changes to each of the affected parts are provided in Appendix A.

The selected manufacturing site, LED die and epoxy are qualified per Broadcom's qualification process.

Reasons for Change:

Discontinuity of existing manufacturing site, LED die and epoxy

Effect of Change on Fit, Form, Function, Quality, or Reliability:

Refer to Appendix A for details.

Effective Date of Change:

Effective 1-July-2024.

Broadcom will continue to ship both existing and new parts after the implementation date until the inventories of the existing parts are fully depleted. Customer is advised not to mix existing and new LED during assembly.

Qualification Data:

Qualification data will be provided upon request.

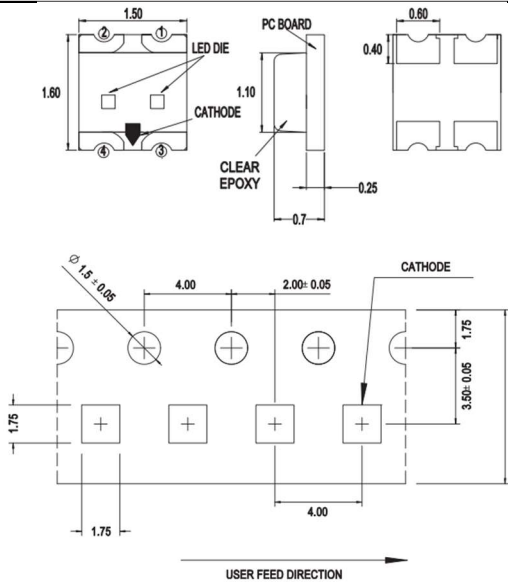
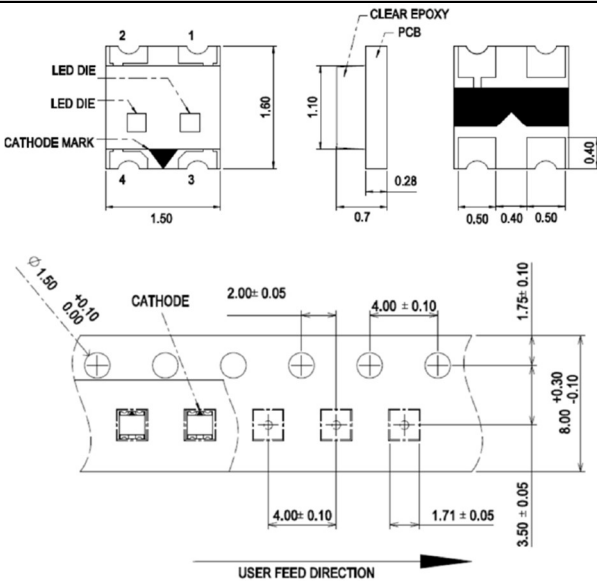
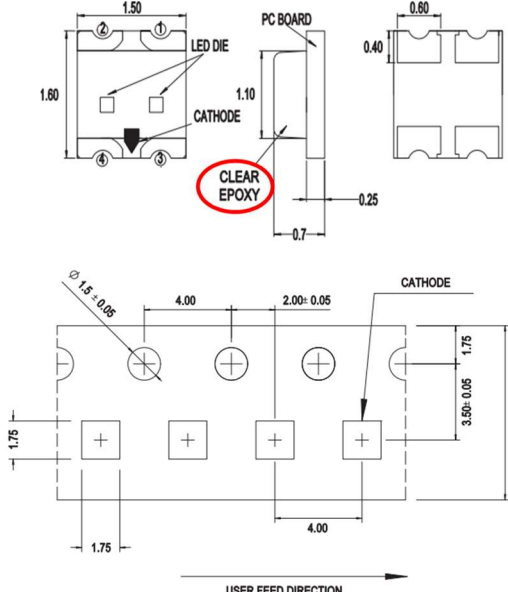
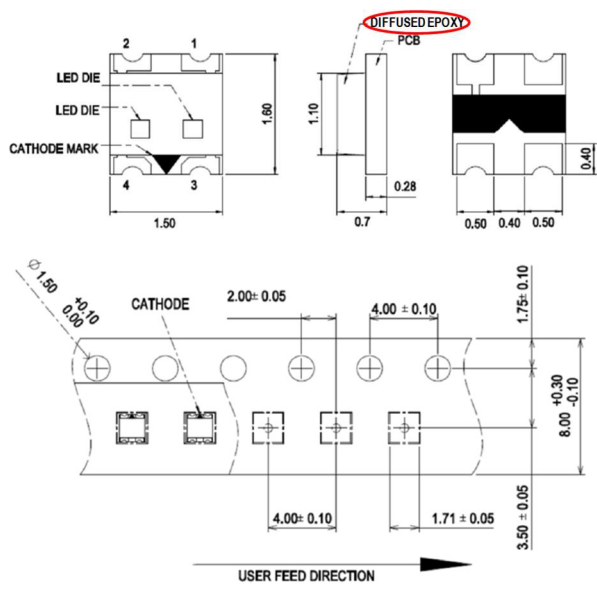
Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.

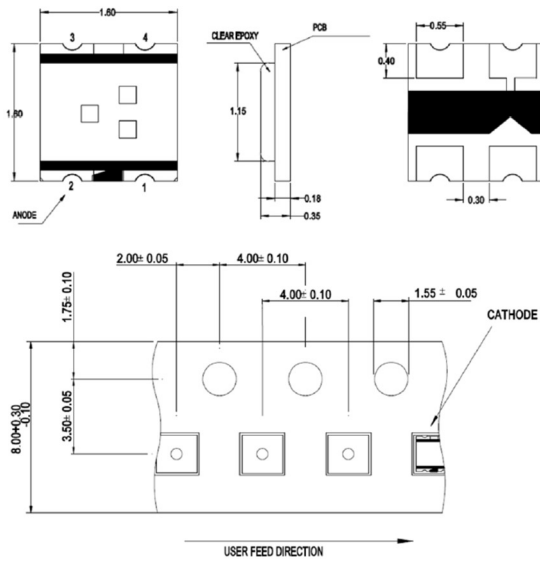
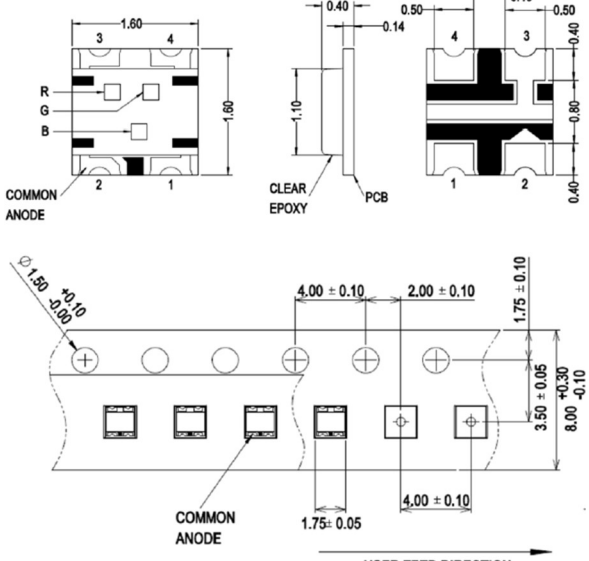
Appendix A:

Details of change in Fit, Form, Function and Product Handling

Section A:

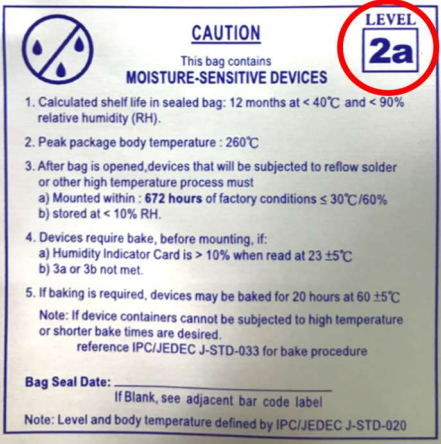

Changes to product appearance and carrier tape.

Affected Parts	Existing	New
HSMF-C180 HSMF-C181 HSMF-C182 BSMF-C183 HSMF-C184 HSMF-C185 HSMF-C188 QSMF-C182-000C1 BSMF-C18B-000AA		
HSMF-C186 HSMF-C187 HSMF-C189		

Affected Parts	Existing	New
HSMF-C124 BSMF-C124		

Section B:
Changes to COO and MSL

Affected Parts	Existing	New
HSMF-C180 HSMF-C181 HSMF-C182 BSMF-C183 HSMF-C184 HSMF-C185 HSMF-C186 HSMF-C187 HSMF-C188 HSMF-C189 QSMF-C182-000C1 BSMF-C18B-000AA HSMQ-C380 QSMQ-V381 HSMF-C124 BSMF-C124		

Affected Parts	Existing	New
HSMF-C186 HSMF-C187 HSMF-C189 HSMF-C124 BSMF-C124	 <p>CAUTION This bag contains MOISTURE-SENSITIVE DEVICES</p> <p>LEVEL 2a</p> <ol style="list-style-type: none"> 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH). 2. Peak package body temperature : 260°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must <ol style="list-style-type: none"> a) Mounted within : 672 hours of factory conditions ≤ 30°C /60% b) stored at < 10% RH. 4. Devices require bake, before mounting, if: <ol style="list-style-type: none"> a) Humidity Indicator Card is > 10% when read at 23 ±5°C b) 3a or 3b not met. 5. If baking is required, devices may be baked for 20 hours at 60 ±5°C <p>Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure</p> <p>Bag Seal Date: _____ (If Blank, see adjacent bar code label)</p> <p>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</p>	 <p>CAUTION This bag contains MOISTURE-SENSITIVE DEVICES</p> <p>LEVEL 4</p> <ol style="list-style-type: none"> 1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH). 2. Peak package body temperature : 260°C 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must <ol style="list-style-type: none"> a) Mounted within : 72 hours of factory conditions < 30°C /60% b) stored at < 10% RH. 4. Devices require bake, before mounting, if: <ol style="list-style-type: none"> a) Humidity Indicator Card is > 10% when read at 23 ±5°C b) 3a or 3b not met. 5. If baking is required, devices may be baked for 20 hours at 60 ±5°C <p>Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure</p> <p>Bag Seal Date: _____ (If Blank, see adjacent bar code label)</p> <p>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</p>

Section C:

Changes to Luminous Intensity

Affected Parts	Existing	New
HSMF-C181	Yellow Green: 4.5 – 28.5 mcd (J, K, L, M) Red: 2.8 – 18 mcd (H, J, K, L)	Yellow Green: 4.5 – 28.5 mcd (J, K, L, M) Red: 7.2 – 45 mcd (K, L, M, N)
HSMQ-C380	1800 – 7150 mcd (X, Y, Z)	Min. 7150 mcd (1 & above)
QSMQ-V381	1800 – 7150 mcd (X, Y, Z)	Min. 7150 mcd (1 & above)